

HRU0103A

Silicon Schottky Barrier Diode for Rectifying

REJ03G0149-0200Z

(Previous: ADE-208-450A)

Rev.2.00 Nov.26.2003

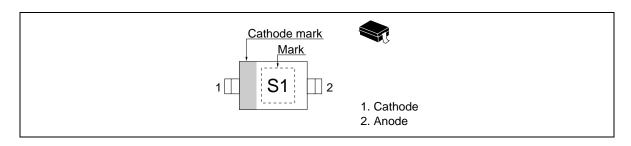
Features

- Low forward voltage drop and suitable for high efficiency rectifying.
- Ultra small Resin Package (URP) is suitable for high density surface mounting and high speed assembly.

Ordering Information

Type No.	Laser Mark	Package Code	
HRU0103A	S1	URP	

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit	
Repetitive peak reverse voltage	V _{RRM} * ¹	30	V	
Average rectified current	I _O *1	100	mA	
Non-Repetitive peak forward surge current	I _{FSM} *2	3	А	
Junction temperature	Tj	125	°C	
Storage temperature	Tstg	-55 to +125	°C	

Notes: 1. See from Fig.3 to Fig.5.

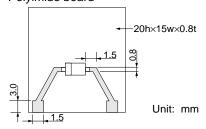
2. 10 ms sine wave 1 pulse.

Electrical Characteristics

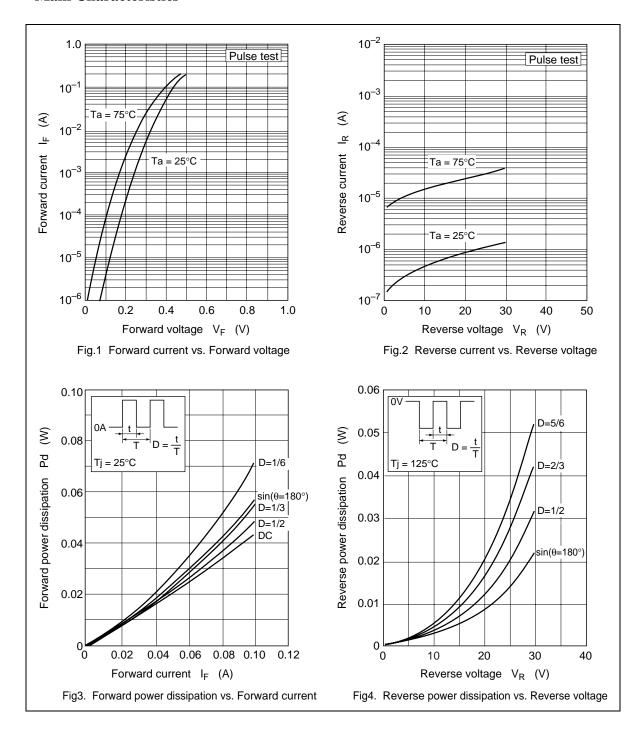
 $(Ta = 25^{\circ}C)$

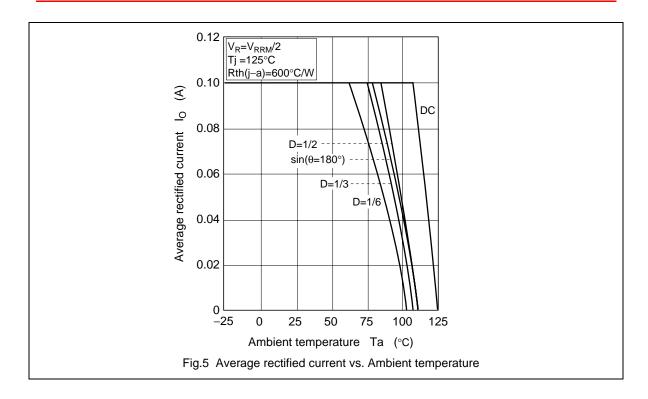
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Forward voltage	V _F	_	_	0.44	V	I _F = 100 mA
Reverse current	I _R	_	_	50	μΑ	V _R = 30 V
Thermal resistance	Rth(j-a)	_	600	_	°C/W	Polyimide board *1

Note: 1. Polyimide board

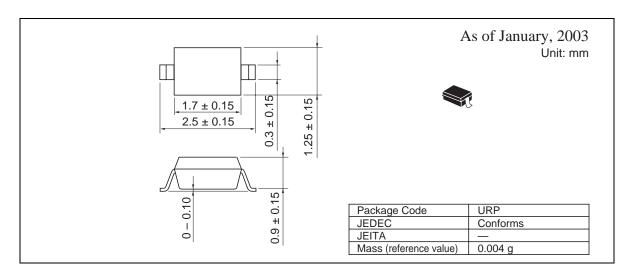


Main Characteristics





Package Dimensions



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